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TABLE OF CONTENTS

VOLUME 1

AI IN HARDWARE & PCB DESIGN.....	1
<i>E. Pierce</i>	
AVOIDING ASSEMBLY PITFALLS: MAXIMIZE FIRST BUILD YIELD!	54
<i>K. Coates</i>	
BASICS OF FLEX DESIGN	79
<i>L. Waslick</i>	
BEYOND THE LAYERS ADVANCED TECHNIQUES FOR PCB STACK-UP DESIGN.....	96
<i>T. Hopkins</i>	
THE MYSTERY OF BYPASS CAPACITORS.....	144
<i>K. Coates</i>	
BRIDGING THE GAP: STRATEGIES FOR EFFECTIVE PCB DESIGN WITH PRE-EXISTING SCHEMATICS	172
<i>L. Waslick, K. Aguiar</i>	
BUILDING A BRIDGE FROM DESIGN TO MANUFACTURE.....	195
<i>S. Webb</i>	
CIRCUIT GROUNDING TO CONTROL NOISE AND EMI.....	280
<i>R. Hartley</i>	
DDR5 THROUGH THE EYES OF THE DESIGNER	338
<i>C. McCauley, T. Duffy</i>	
DESIGN & VERIFICATION OF ULTRA-HDI TOPOLOGIES	371
<i>S. Chavez</i>	
DESIGN FOR SOURCING	379
<i>E. Dodd</i>	
DESIGN IN 3D -BREAKING THE MOLD	420
<i>S. Schmidt</i>	
DFM FOR ULTRA-HDI	469
<i>S. Chavez</i>	
DIFFERENTIAL PAIR DESIGN FOR 112 GBPS AND FASTER SYSTEMS.....	479
<i>Z. Peterson</i>	
DIFFERENTIAL PAIR ROUTING FOR SIGNAL INTEGRITY AND EMI CONTROL	517
<i>R. Hartley</i>	
DISPELLING THE MYTHS AND MYSTERIES OF POWER DISTRIBUTION NETWORKS	549
<i>J. Eck</i>	

EFFECTIVE PRINTED CIRCUIT BOARD DESIGN: TECHNIQUES TO IMPROVE PERFORMANCE	574
<i>D. Beeker</i>	

EMC IS NOT BLACK MAGIC...NO MATTER HOW MUCH IT SEEMS THAT WAY	658
<i>K. Burnham</i>	

VOLUME 2

ENHANCING PCB PRODUCTION: ADDED VALUE AND NEW FEATURES BY INKJET - THE FUTURE OF ADDITIVE MANUFACTURING	753
<i>M. Mosberg</i>	

FEEDING THE HUNGRY LION - POWER DELIVERY SYSTEM DESIGN FOR TODAY'S DEMANDING MODERN ICS	772
<i>C. Corley</i>	

FLEXIBLE CIRCUITS DESIGN THROUGH TEST WITH LESSONS LEARNED.....	889
<i>M. Finstad, N. Koop</i>	

HARNESSING THE POWER OF AI IN PCB DESIGN: ADDRESSING CHALLENGES & UNLOCKING OPPORTUNITIES.....	948
<i>D. Wiens</i>	

HDI VIA DESIGN: PLANNING THE ENERGY PIPELINES	962
<i>D. Beeker</i>	

HIGH POWER PCB DESIGN: PUSHING THE LIMITS.....	1006
<i>C. Buck</i>	

AN INTUITIVE APPROACH TO UNDERSTANDING HIGH SPEED LAYOUT (THE BASICS FROM ANOTHER PERSPECTIVE).....	1031
<i>K. Coates</i>	

HOW CAN WE MITIGATE CORROSION IN ENIG SURFACES THROUGH INNOVATIVE PROCESS MANAGEMENT? A DESIGN OF EXPERIMENTS APPROACH.....	1076
<i>H. Zimmerman, R. Wieland</i>	

HOW PCB DESIGN AFFECTS FABRICATION.....	1086
<i>P. Cooke</i>	

IMPROVING CIRCUIT DESIGN AND LAYOUT: STRATEGIES FOR ENHANCED ACCESSIBILITY AND SUCCESS	1389
<i>T. Chester</i>	

MASTERING DESIGN RULE CHECK (DRC): SETTINGS FOR OPTIMAL PCB DESIGN	1424
<i>T. Hopkins</i>	

VOLUME 3

MASTERING SIGNAL INTEGRITY ANALYSIS: A PRACTICAL GUIDE FOR PCB DESIGNERS	1453
<i>T. Lee</i>	

MIXED SIGNAL DESIGNS.....	1524
<i>K. Kowal</i>	
PCB DESIGN FOR ENGINEERS	1558
<i>S. Webb</i>	
PC BOARD LAYOUT OF SWITCH MODE POWER SUPPLIES.....	1689
<i>R. Hartley</i>	
PICOSECOND LASER DRILLING FOR IMPROVED MICROVIA PERFORMANCE AND RELIABILITY	1726
<i>B. Solari</i>	
PIONEERING SOLUTIONS IN COMPLEX PCB DESIGN FOR NEXT-GEN TECHNOLOGY	1745
<i>S. Chavez</i>	
RESOLVING BOARD DESIGN CONGESTION WITH GRID SYSTEMS	1769
<i>S. Webb</i>	
RF / MICROWAVE AND MIXED SIGNAL PC BOARD DESIGN	1854
<i>R. Hartley</i>	
SIGNAL INTEGRITY IN UHDI PCBs AND IC SUBSTRATES.....	1917
<i>Z. Peterson</i>	
STACKING THE DECK: MAXIMIZING THE PCB LAYER DESIGN FOR BEST SIGNAL INTEGRITY AND EMC PERFORMANCE.....	1971
<i>D. Beeker</i>	
THE STATE OF HARDWARE 2025: 1,000 ENGINEERS ON TRENDS, CHALLENGES, AND TOOLSETS	1992
<i>V. Ratner</i>	
THE 21 MOST COMMON DESIGN ERRORS, CAUGHT BY FABRICATION (AND HOW TO PREVENT THEM).....	2004
<i>M. Tucker, R. Fugitt</i>	
THE FUTURE OF PCB DESIGN.....	2029
<i>M. Leary</i>	
THE IMPORTANCE OF FABRICATION AND ASSEMBLY DRAWINGS	2040
<i>J. Frias</i>	
THE UNSUNG HERO: VIA'S VITAL ROLE IN PCB RETURN PATHS.....	2054
<i>R. Hartley</i>	
HEAT MANAGEMENT FOR SMD, LED, AND SYSTEMS IN 1W - 50W SECTIONS (DO NOT LET THE SMOKE OUT!)	2073
<i>K. Coates</i>	

Author Index